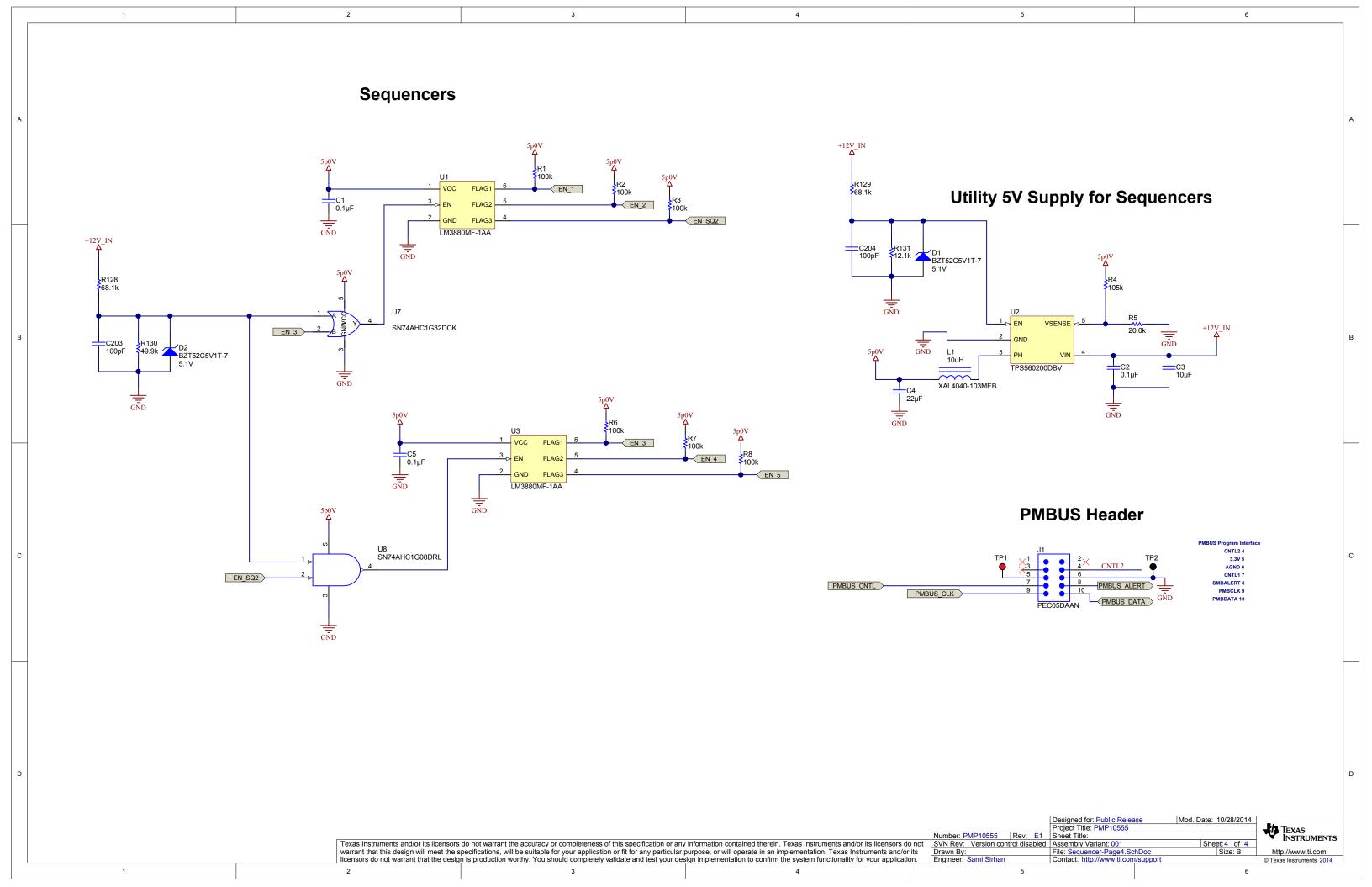
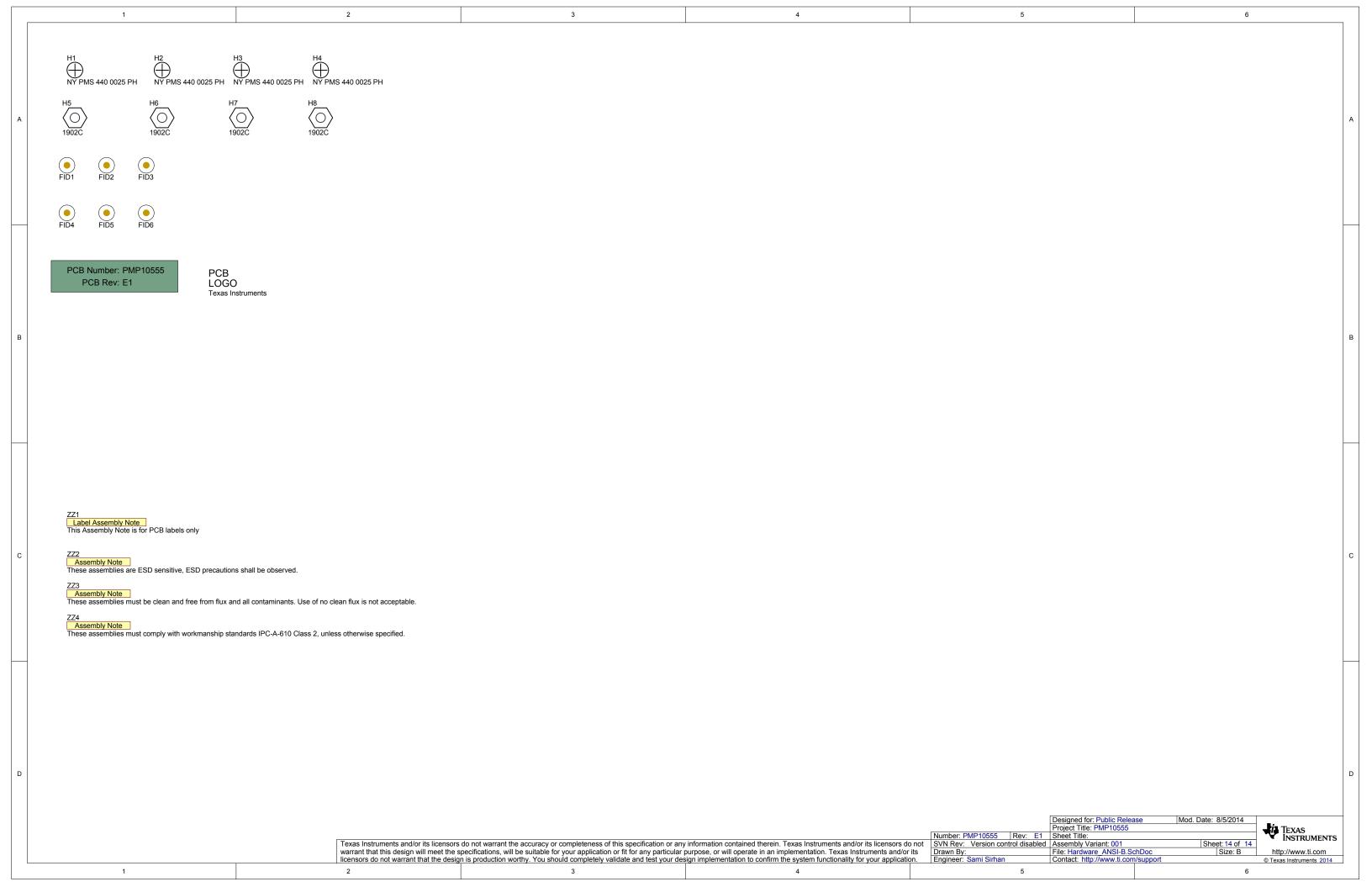


MGTVCCAUX + VCCO: +1.8V@2.5A MGTAVTT: +1.2V@1A VCCO\_PSIO: +3.3V@0.5A Place 22uF cap near PVIN1 Place 4.7uF cap near PVIN3 +12V\_IN Iripple = ~0.71A L10 4.7uH VCCO\_1p8V +1.8V/2.5A ±C57 47μF 12 PVIN2 13 PVIN3 0.047uF \_C59 \_\_\_C60  $\overline{\sim}$ 22µF 10µF 7447779004 C61 100µF =C63 100µF —C62 100μF COMP1 23 COMP1\_2 I GND Iripple = ~0.53A L11 +1.2V/1A 4.7uH MGTAVTT TP17 0.047µF 74408943047 =C67 100µF =C68 100μF =C69 100μF 32 D EN1 EN2 1 D EN3 EN\_3 EN\_5 Iripple = ~0.15A GND **●** TP18 L12 +3.3V/0.5A tss = 1.2ms 33uH VCCO\_PSIO TP19 0.047µF 17 ⊳ SS3 SDR0403-330KL C73 22µF FB3 19 FB3\_2 88.7k PGND1 27 11 14 14 VCCO\_1p8V MGTAVTT VCCO\_PSIO 를 GND TPS65261-1RHB GND TP27 TP28 \\ 49.9 TP8 49.9 FB1\_2 FB2\_2 FB3\_2 10.0k 0.1% 10.0k 0.1% 10.0k GND <u>=</u> GND COMP1\_2 R36 127k 84.5k 17.4k 1800pF Ę GND Mod. Date: 10/28/2014 Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant the accuracy or completeness of the accuracy or completeness of this specification or any information contained therein. Texas Instru TEXAS INSTRUMENTS http://www.ti.com licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.





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